

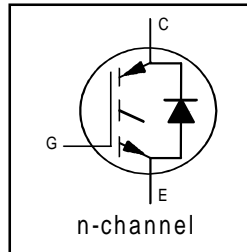
IRG4PC50KD

INSULATED GATE BIPOLAR TRANSISTOR WITH
ULTRAFAST SOFT RECOVERY DIODE

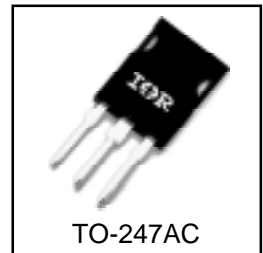
Short Circuit Rated
UltraFast IGBT

Features

- Short Circuit Rated UltraFast: Optimized for high operating frequencies >5.0 kHz, and Short Circuit Rated to 10 μ s @ 125°C, $V_{GE} = 15V$
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than Generation 3
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-247AC package



| |
|-----------------------------|
| $V_{CES} = 600V$ |
| $V_{CE(on) typ.} = 1.84V$ |
| @ $V_{GE} = 15V, I_C = 30A$ |



Benefits

- Generation 4 IGBTs offer highest efficiencies available
- HEXFRED diodes optimized for performance with IGBTs. Minimized recovery characteristics require less/no snubbing
- Designed to be a "drop-in" replacement for equivalent industry-standard Generation 3 IR IGBTs

Absolute Maximum Ratings

| | Parameter | Max. | Units |
|---------------------------|------------------------------------|-----------------------------------|------------|
| V_{CES} | Collector-to-Emitter Voltage | 600 | V |
| $I_C @ T_C = 25^\circ C$ | Continuous Collector Current | 52 | A |
| $I_C @ T_C = 100^\circ C$ | Continuous Collector Current | 30 | |
| I_{CM} | Pulsed Collector Current ① | 104 | |
| I_{LM} | Clamped Inductive Load Current ② | 104 | |
| $I_F @ T_C = 100^\circ C$ | Diode Continuous Forward Current | 25 | |
| I_{FM} | Diode Maximum Forward Current | 280 | |
| t_{sc} | Short Circuit Withstand Time | 10 | μ s |
| V_{GE} | Gate-to-Emitter Voltage | ± 20 | V |
| $P_D @ T_C = 25^\circ C$ | Maximum Power Dissipation | 200 | W |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation | 78 | |
| T_J | Operating Junction and | -55 to +150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | | |
| | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) | |
| | Mounting Torque, 6-32 or M3 Screw. | 10 lbf•in (1.1 N•m) | |

Thermal Resistance

| | Parameter | Min. | Typ. | Max. | Units |
|-----------------|---|------|----------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case - IGBT | — | — | 0.64 | $^\circ C/W$ |
| $R_{\theta JC}$ | Junction-to-Case - Diode | — | — | 0.83 | |
| $R_{\theta CS}$ | Case-to-Sink, flat, greased surface | — | 0.24 | — | |
| $R_{\theta JA}$ | Junction-to-Ambient, typical socket mount | — | — | 40 | |
| Wt | Weight | — | 6 (0.21) | — | g (oz) |

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--|--|------|------|------|-------|--|
| V _{(BR)CES} | Collector-to-Emitter Breakdown Voltage ③ | 600 | — | — | V | V _{GE} = 0V, I _C = 250μA |
| DV _{(BR)CES} /DT _J | Temperature Coeff. of Breakdown Voltage | — | 0.47 | — | V/°C | V _{GE} = 0V, I _C = 1.0mA |
| V _{CE(on)} | Collector-to-Emitter Saturation Voltage | — | 1.84 | 2.2 | V | I _C = 30A V _{GE} = 15V |
| | | — | 2.19 | — | | I _C = 52A see figures 2, 5 |
| | | — | 1.79 | — | | I _C = 25A, T _J = 150°C |
| V _{GE(th)} | Gate Threshold Voltage | 3.0 | — | 6.0 | | V _{CE} = V _{GE} , I _C = 250μA |
| DV _{GE(th)} /DT _J | Temperature Coeff. of Threshold Voltage | — | -12 | — | mV/°C | V _{CE} = V _{GE} , I _C = 250μA |
| g _{fe} | Forward Transconductance ④ | 17 | 24 | — | S | V _{CE} = 100V, I _C = 30A |
| I _{CES} | Zero Gate Voltage Collector Current | — | — | 250 | μA | V _{GE} = 0V, V _{CE} = 600V |
| | | — | — | 6500 | | V _{GE} = 0V, V _{CE} = 600V, T _J = 150°C |
| V _{FM} | Diode Forward Voltage Drop | — | 1.3 | 1.7 | V | I _C = 25A see figure 13 |
| | | — | 1.2 | 1.5 | | I _C = 25A, T _J = 150°C |
| I _{GES} | Gate-to-Emitter Leakage Current | — | — | ±100 | nA | V _{GE} = ±20V |

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------------------|---|------|------|------|---------------------|--|
| Q _g | Total Gate Charge (turn-on) | — | 200 | 300 | nC | I _C = 30A |
| Q _{ge} | Gate - Emitter Charge (turn-on) | — | 25 | 38 | | V _{CC} = 400V see figure 8 |
| Q _{gc} | Gate - Collector Charge (turn-on) | — | 85 | 127 | | V _{GE} = 15V |
| t _{d(on)} | Turn-On Delay Time | — | 63 | — | ns | T _J = 25°C I _C = 30A, V _{CC} = 480V V _{GE} = 15V, R _G = 5.0Ω |
| t _r | Rise Time | — | 49 | — | | |
| t _{d(off)} | Turn-Off Delay Time | — | 150 | 220 | | |
| t _f | Fall Time | — | 95 | 140 | | |
| E _{on} | Turn-On Switching Loss | — | 1.61 | — | | |
| E _{off} | Turn-Off Switching Loss | — | 0.84 | — | mJ | Energy losses include "tail" and diode reverse recovery |
| E _{ts} | Total Switching Loss | — | 2.45 | 3.0 | see figures 9,10,18 | |
| t _{sc} | Short Circuit Withstand Time | 10 | — | — | μs | V _{CC} = 360V, T _J = 125°C V _{GE} = 15V, R _G = 10Ω, V _{CPK} < 500V |
| t _{d(on)} | Turn-On Delay Time | — | 61 | — | ns | T _J = 150°C, see figures 11,18 I _C = 30A, V _{CC} = 480V V _{GE} = 15V, R _G = 5.0Ω Energy losses include "tail" and diode reverse recovery |
| t _r | Rise Time | — | 46 | — | | |
| t _{d(off)} | Turn-Off Delay Time | — | 310 | — | | |
| t _f | Fall Time | — | 170 | — | | |
| E _{ts} | Total Switching Loss | — | 3.53 | — | | |
| L _E | Internal Emitter Inductance | — | 13 | — | nH | Measured 5mm from package |
| C _{ies} | Input Capacitance | — | 3200 | — | pF | V _{GE} = 0V V _{CC} = 30V see figure 7 f = 1.0MHz |
| C _{oes} | Output Capacitance | — | 370 | — | | |
| C _{res} | Reverse Transfer Capacitance | — | 95 | — | | |
| t _{rr} | Diode Reverse Recovery Time | — | 50 | 75 | ns | T _J = 25°C see figure |
| | | — | 105 | 160 | | T _J = 125°C 14 |
| I _{rr} | Diode Peak Reverse Recovery Current | — | 4.5 | 10 | A | T _J = 25°C see figure |
| | | — | 8.0 | 15 | | T _J = 125°C 15 |
| Q _{rr} | Diode Reverse Recovery Charge | — | 112 | 375 | nC | T _J = 25°C see figure |
| | | — | 420 | 1200 | | T _J = 125°C 16 |
| di _(rec) M/dt | Diode Peak Rate of Fall of Recovery During t _b | — | 250 | — | A/μs | T _J = 25°C see figure |
| | | — | 160 | — | | T _J = 125°C 17 |

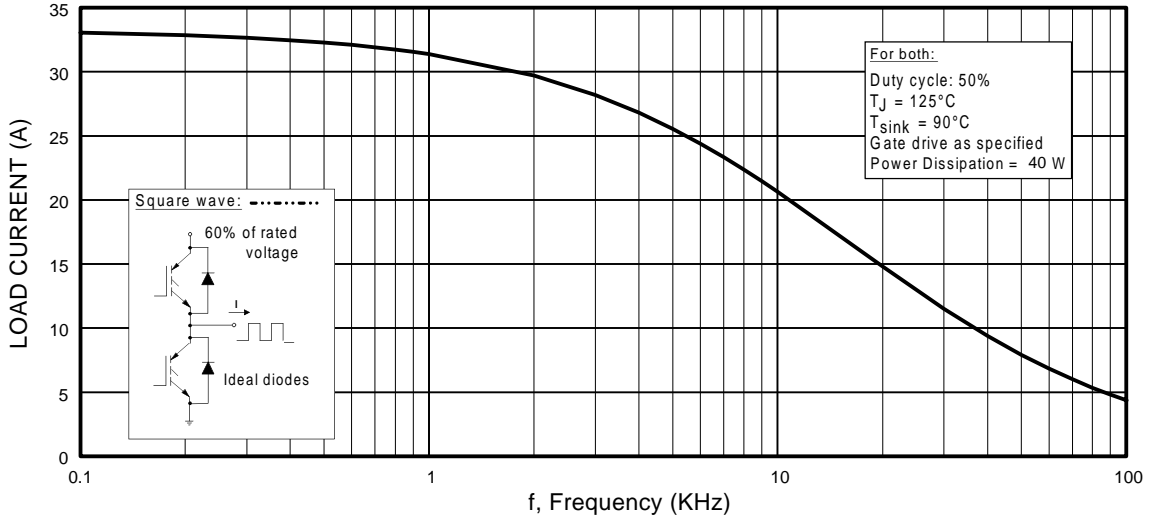


Fig. 1 - Typical Load Current vs. Frequency
 (Load Current = I_{RMS} of fundamental)

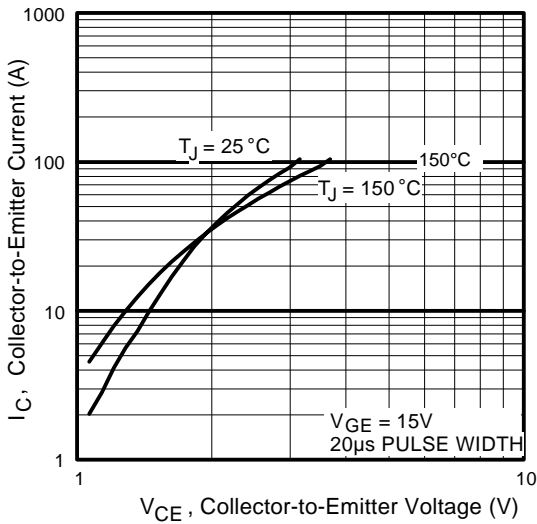


Fig. 2 - Typical Output Characteristics

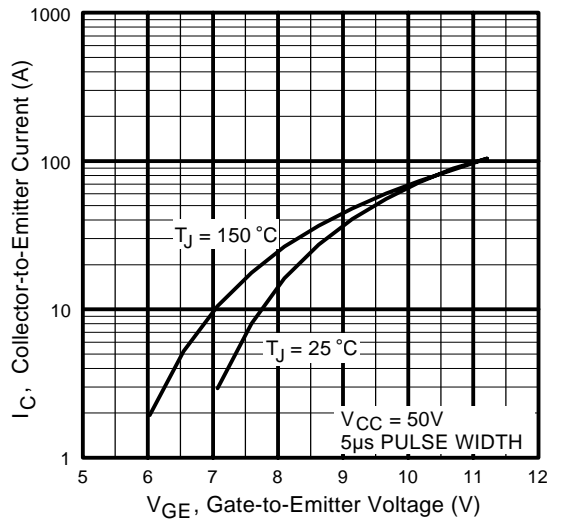


Fig. 3 - Typical Transfer Characteristics

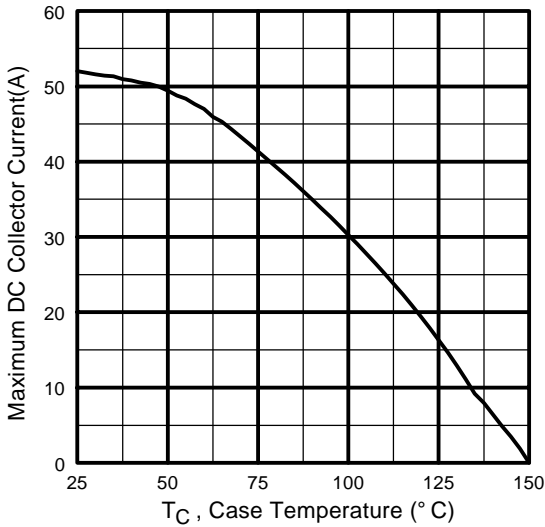


Fig. 4 - Maximum Collector Current vs. Case Temperature

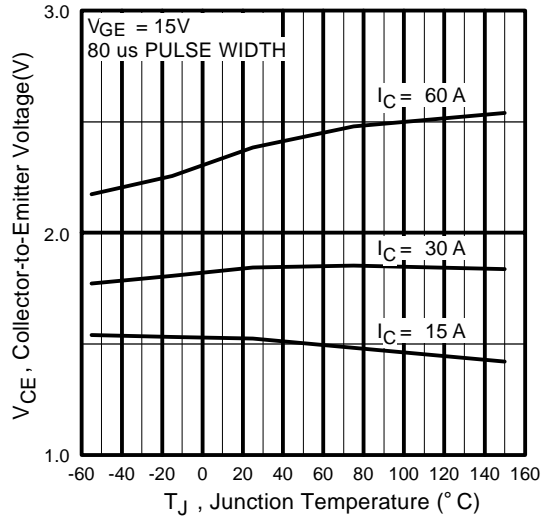


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

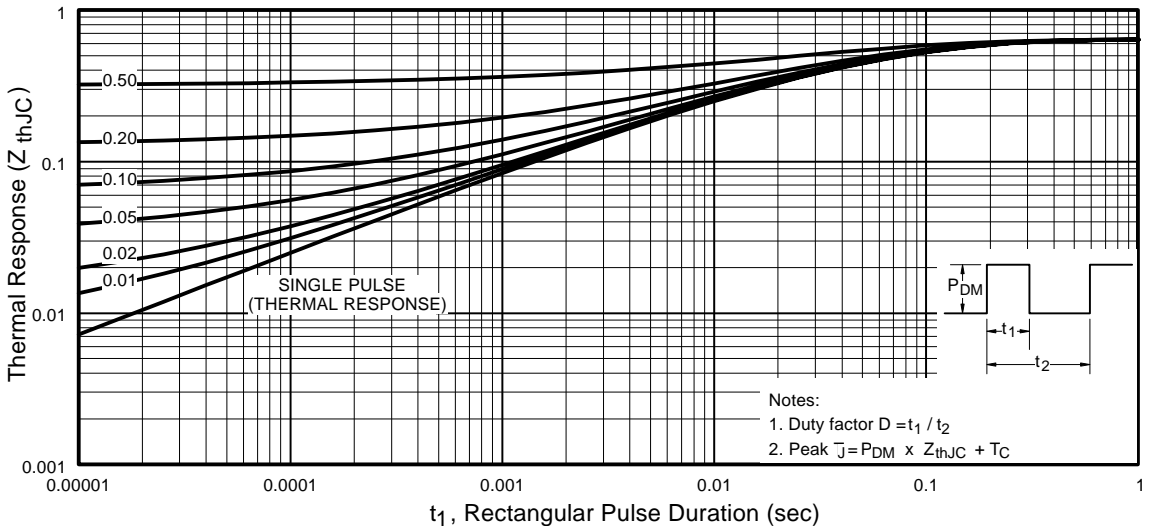


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

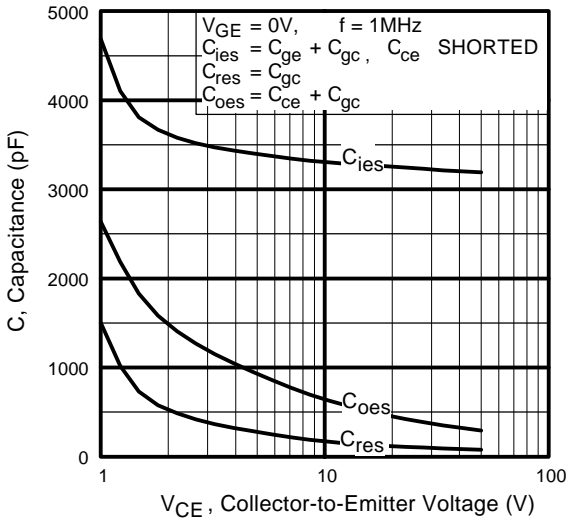


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

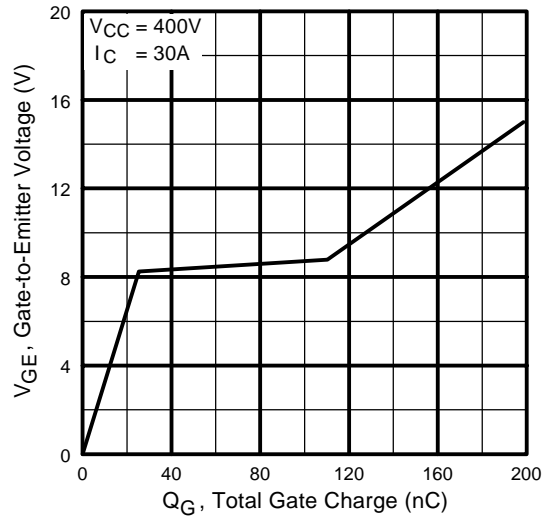


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

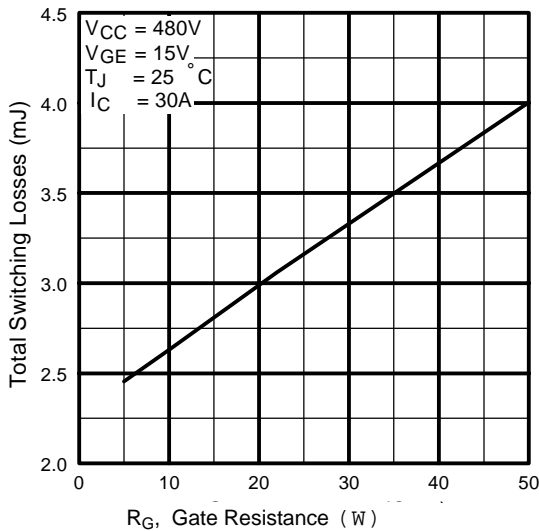


Fig. 9 - Typical Switching Losses vs. Gate Resistance

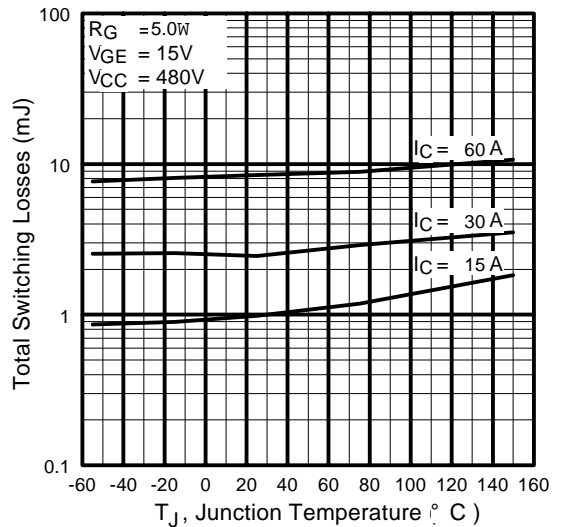


Fig. 10 - Typical Switching Losses vs. Junction Temperature

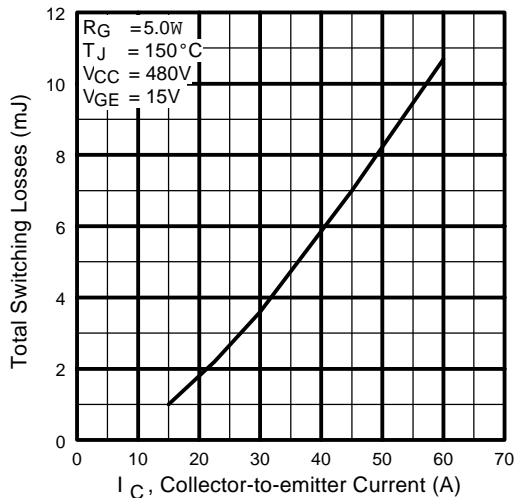


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

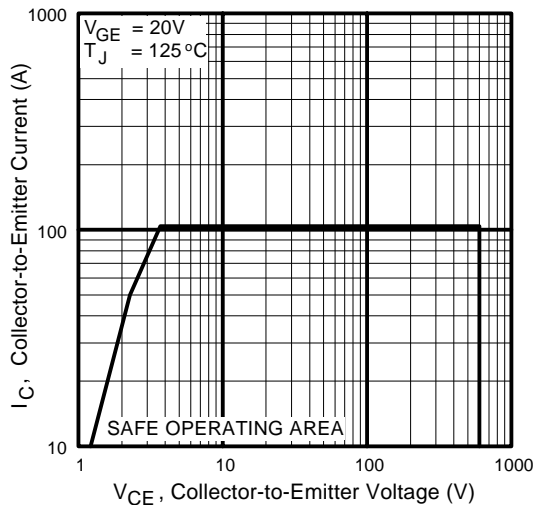


Fig. 12 - Turn-Off SOA

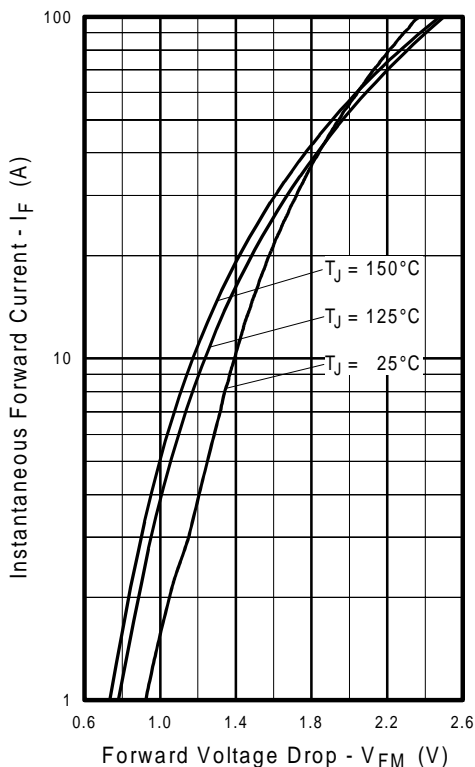


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

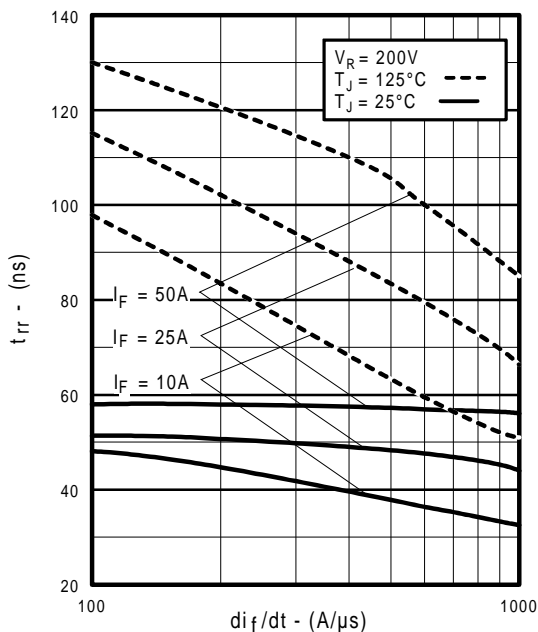


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

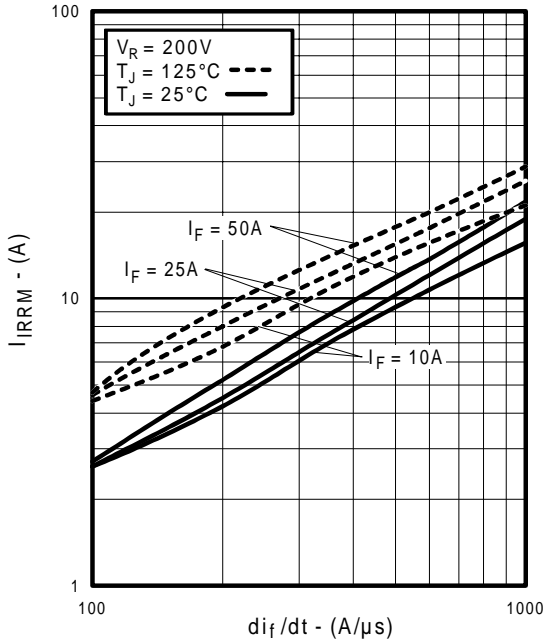


Fig. 15 - Typical Recovery Current vs. di_f/dt

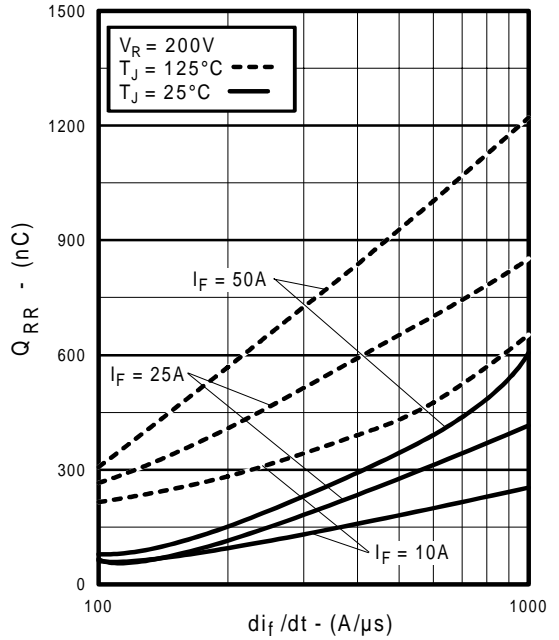


Fig. 16 - Typical Stored Charge vs. di_f/dt

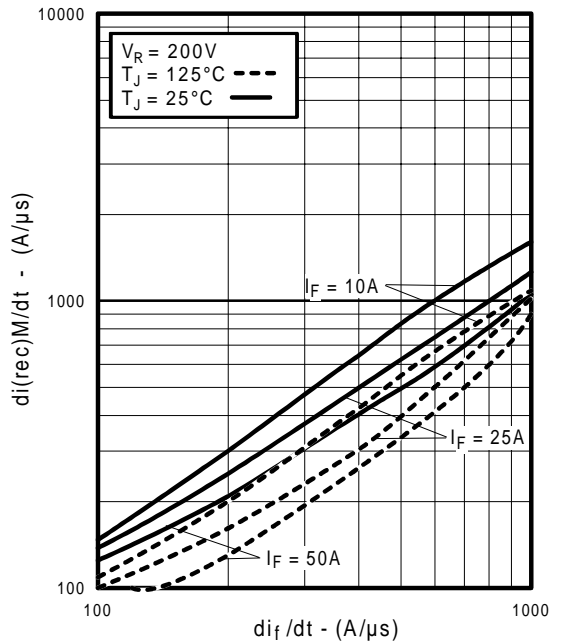


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

Mechanical drawings, Appendix A
 Test Circuit diagrams, Appendix B
 Switching Loss Waveforms, Appendix C

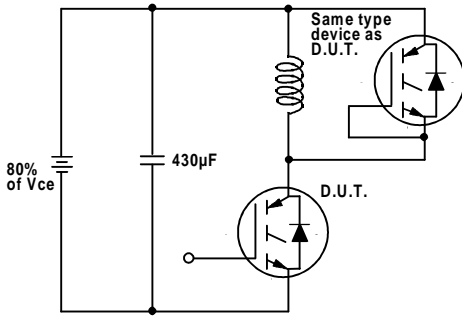


Fig. 18a - Test Circuit for Measurement of I_{LM} , E_{on} , $E_{off(diode)}$, t_{rr} , Q_{rr} , I_{rr} , $t_{d(on)}$, t_r , $t_{d(off)}$, t_f

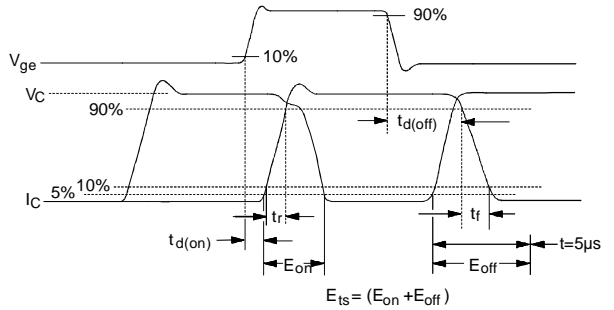


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off} , $t_{d(off)}$, t_f

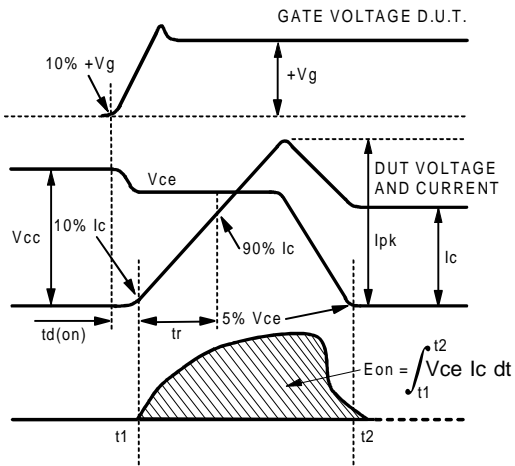


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

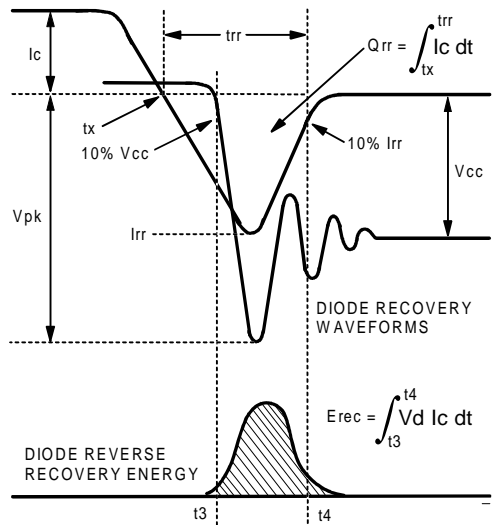


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_{rr} , I_{rr}

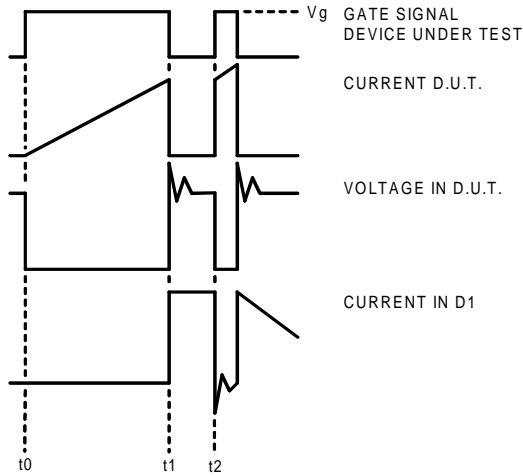


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

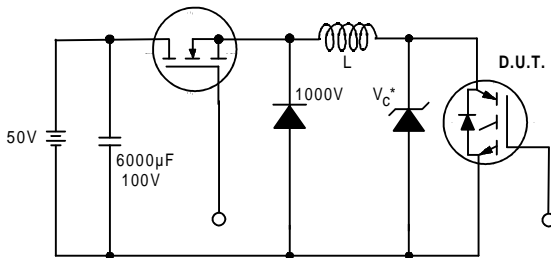


Figure 19. Clamped Inductive Load Test Circuit

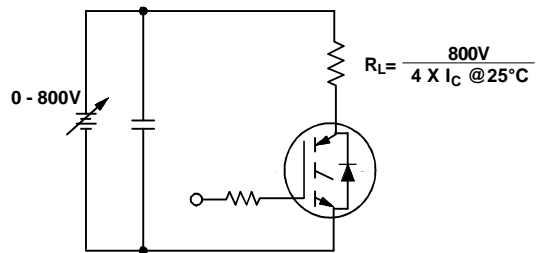
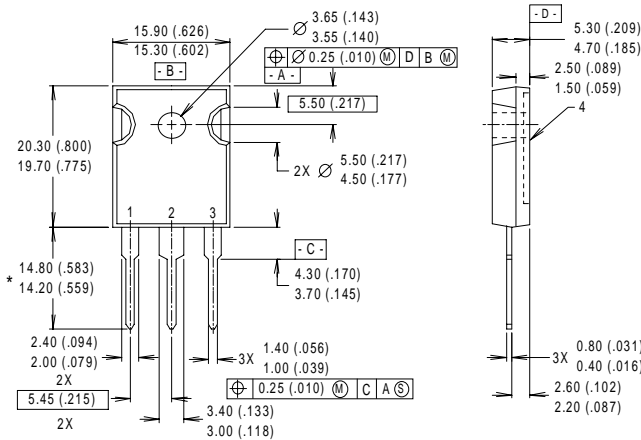


Figure 20. Pulsed Collector Current Test Circuit

Notes:

- ① Repetitive rating: $V_{GE}=20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC}=80\% (V_{CES})$, $V_{GE}=20V$, $I=10\mu H$, $R_G=5.0W$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

Case Outline — TO-247AC



- NOTES:
- 1 DIMENSIONS & TOLERANCING PER ANSI Y14.5M, 1982.
 - 2 CONTROLLING DIMENSION : INCH.
 - 3 DIMENSIONS ARE SHOWN MILLIMETERS (INCHES).
 - 4 CONFORMS TO JEDEC OUTLINE TO-247AC.

- LEAD ASSIGNMENTS
- 1 - GATE
 - 2 - COLLECTOR
 - 3 - EMITTER
 - 4 - COLLECTOR

* LONGER LEADED (20mm) VERSION AVAILABLE (TO-247AD) TO ORDER ADD "E" SUFFIX TO PART NUMBER

CONFORMS TO JEDEC OUTLINE TO-247AC (TO-3P)
Dimensions in Millimeters and (Inches)

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IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

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IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 838 4630

IR TAIWAN: 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan Tel: 886-2-2377-9936

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